



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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SUMMARY
 $V_{(BR)DSS} = -30V$; $R_{DS(ON)} = 0.040\Omega$; $I_D = -6.7A$
DESCRIPTION

This new generation of trench MOSFETs from Zetex utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.

FEATURES

- Low on-resistance
- Fast switching speed
- Low threshold
- Low gate drive
- Low profile SOIC package

APPLICATIONS

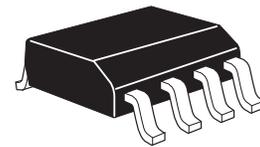
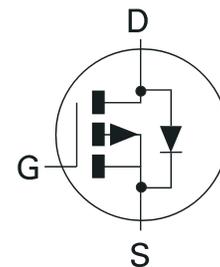
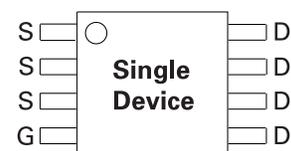
- Disconnect switches
- Motor control

ORDERING INFORMATION

| DEVICE | REEL SIZE | TAPE WIDTH | QUANTITY PER REEL |
|-----------------|-----------|------------|-------------------|
| NK-ZXMP3A16N8TA | 7" | 12mm | 500 units |
| NK-ZXMP3A16N8TC | 13" | 12mm | 2500 units |

DEVICE MARKING

- NK-ZXMP
3A16


SO8

PINOUT


Top View

ABSOLUTE MAXIMUM RATINGS

| PARAMETER | SYMBOL | LIMIT | UNIT |
|---|----------------|----------------------|----------------------|
| Drain-Source Voltage | V_{DSS} | -30 | V |
| Gate Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current $V_{GS}=-10V; T_A=25^{\circ}C$ (b) $V_{GS}=-10V; T_A=70^{\circ}C$ (b) $V_{GS}=-10V; T_A=25^{\circ}C$ (a) | I_D | -6.7 -5.4 -5.6 | A |
| Pulsed Drain Current (c) | I_{DM} | -26 | A |
| Continuous Source Current (Body Diode) (b) | I_S | -3.2 | A |
| Pulsed Source Current (Body Diode) (c) | I_{SM} | -26 | A |
| Power Dissipation at $T_A=25^{\circ}C$ (a) Linear Derating Factor | P_D | 1.9 15.2 | W mW/ $^{\circ}C$ |
| Power Dissipation at $T_A=25^{\circ}C$ (b) Linear Derating Factor | P_D | 2.8 22.4 | W mW/ $^{\circ}C$ |
| Operating and Storage Temperature Range | $T_j; T_{stg}$ | -55 to +150 | $^{\circ}C$ |

THERMAL RESISTANCE

| PARAMETER | SYMBOL | VALUE | UNIT |
|-------------------------|-----------------|-------|---------------|
| Junction to Ambient (a) | $R_{\theta JA}$ | 65 | $^{\circ}C/W$ |
| Junction to Ambient (b) | $R_{\theta JA}$ | 45 | $^{\circ}C/W$ |

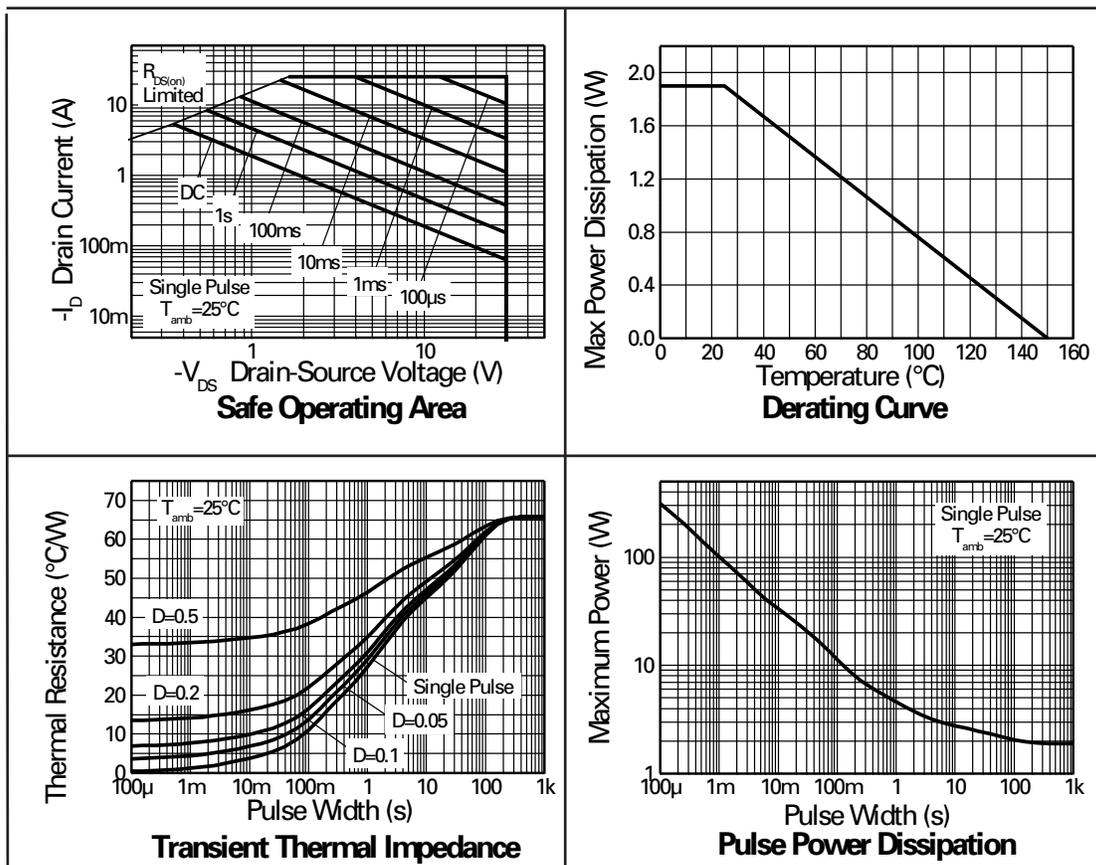
NOTES

(a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions

(b) For a device surface mounted on FR4 PCB measured at $t \leq 5$ secs.

(c) Repetitive rating 25mm x 25mm FR4 PCB, $D = 0.05$, pulse width $10 \mu s$ - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.

CHARACTERISTICS



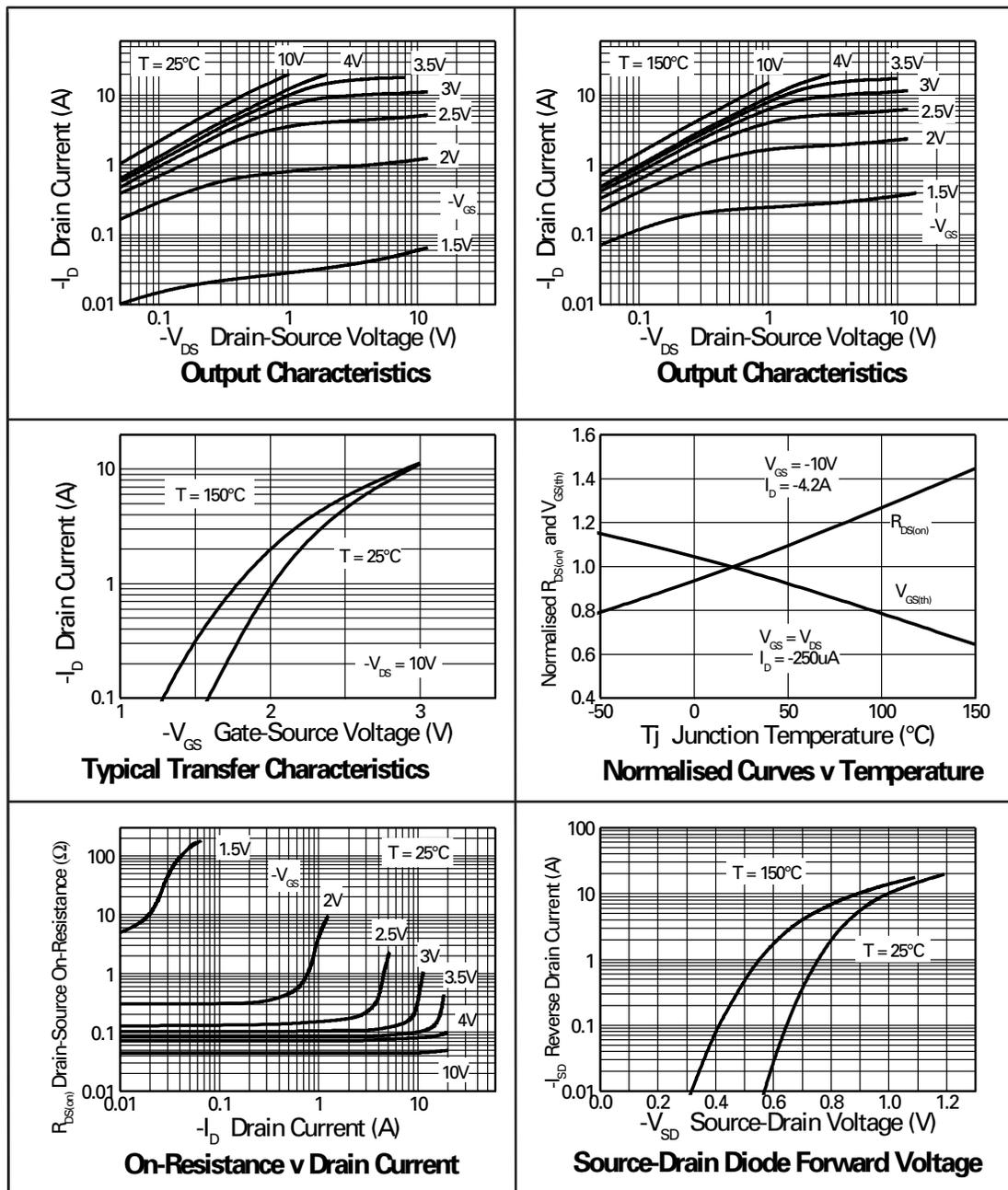
ELECTRICAL CHARACTERISTICS (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

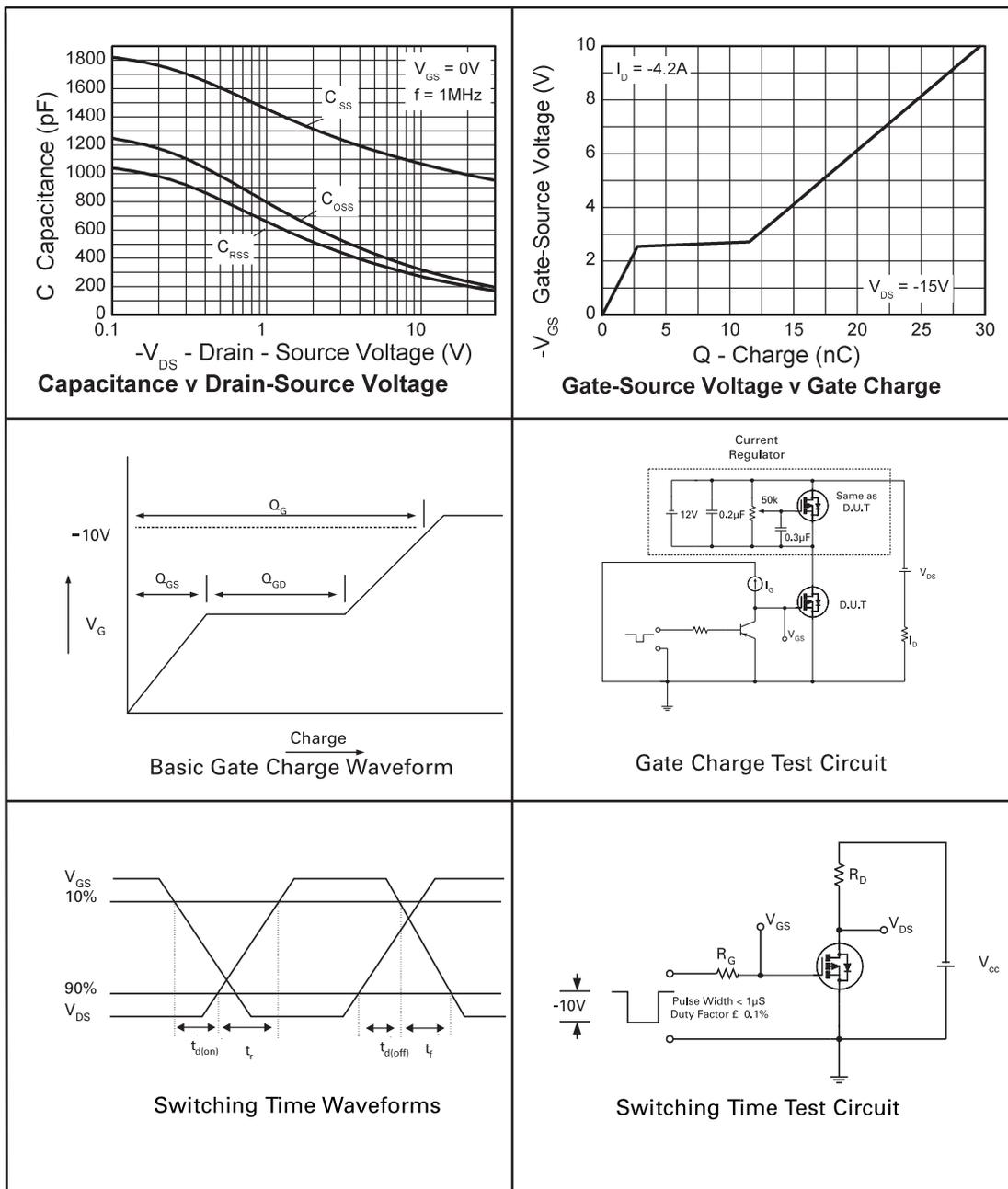
| PARAMETER | SYMBOL | MIN. | TYP. | MAX. | UNIT | CONDITIONS |
|---|---------------|------|-------|----------------|----------------------|---|
| STATIC | | | | | | |
| Drain-Source Breakdown Voltage | $V_{(BR)DSS}$ | -30 | | | V | $I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$ |
| Zero Gate Voltage Drain Current | I_{DSS} | | | -1.0 | μA | $V_{DS} = -30\text{V}, V_{GS} = 0\text{V}$ |
| Gate-Body Leakage | I_{GSS} | | | 100 | nA | $V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$ |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | -1.0 | | | V | $I_D = -250\mu\text{A}, V_{DS} = V_{GS}$ |
| Static Drain-Source On-State Resistance (1) | $R_{DS(on)}$ | | | 0.040 0.070 | Ω Ω | $V_{GS} = -10\text{V}, I_D = -4.2\text{A}$ $V_{GS} = -4.5\text{V}, I_D = -3.4\text{A}$ |
| Forward Transconductance (1)(3) | g_{fs} | | 9.2 | | S | $V_{DS} = -15\text{V}, I_D = -4.2\text{A}$ |
| DYNAMIC (3) | | | | | | |
| Input Capacitance | C_{iss} | | 1022 | | pF | $V_{DS} = -15\text{V}, V_{GS} = 0\text{V},$ $f = 1\text{MHz}$ |
| Output Capacitance | C_{oss} | | 267 | | pF | |
| Reverse Transfer Capacitance | C_{rss} | | 229 | | pF | |
| SWITCHING(2) (3) | | | | | | |
| Turn-On Delay Time | $t_{d(on)}$ | | 3.8 | | ns | $V_{DD} = -15\text{V}, I_D = -1\text{A}$ $R_G = 6.0\Omega, V_{GS} = -10\text{V}$ |
| Rise Time | t_r | | 6.5 | | ns | |
| Turn-Off Delay Time | $t_{d(off)}$ | | 37.1 | | ns | |
| Fall Time | t_f | | 21.4 | | ns | |
| Gate Charge | Q_g | | 17.2 | | nC | $V_{DS} = -15\text{V}, V_{GS} = -5\text{V},$ $I_D = -4.2\text{A}$ |
| Total Gate Charge | Q_g | | 29.6 | | nC | $V_{DS} = -15\text{V}, V_{GS} = -10\text{V},$ $I_D = -4.2\text{A}$ |
| Gate-Source Charge | Q_{gs} | | 2.8 | | nC | |
| Gate-Drain Charge | Q_{gd} | | 8.6 | | nC | |
| SOURCE-DRAIN DIODE | | | | | | |
| Diode Forward Voltage (1) | V_{SD} | | -0.85 | -0.95 | V | $T_J = 25^{\circ}\text{C}, I_S = -3.6\text{A},$ $V_{GS} = 0\text{V}$ |
| Reverse Recovery Time (3) | t_{rr} | | 21.7 | | ns | $T_J = 25^{\circ}\text{C}, I_F = -2\text{A},$ $di/dt = 100\text{A}/\mu\text{s}$ |
| Reverse Recovery Charge (3) | Q_{rr} | | 16.1 | | nC | |

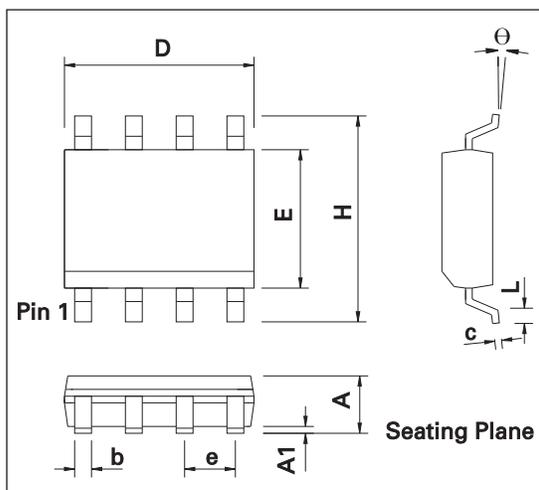
NOTES

- (1) Measured under pulsed conditions. Width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.
 (2) Switching characteristics are independent of operating junction temperature.
 (3) For design aid only, not subject to production testing.

CHARACTERISTICS





PACKAGE OUTLINE


CONTROLLING DIMENSIONS ARE IN INCHES
 APPROX IN MILLIMETERS

PACKAGE DIMENSIONS

| DIM | Millimeters | | Inches | | DIM | Millimeters | | Inches | |
|-----|-------------|------|--------|-------|-----|-------------|------|-----------|-------|
| | Min | Max | Min | Max | | Min | Max | Min | Max |
| A | 1.35 | 1.75 | 0.053 | 0.069 | e | 1.27 BSC | | 0.050 BSC | |
| A1 | 0.10 | 0.25 | 0.004 | 0.010 | b | 0.33 | 0.51 | 0.013 | 0.020 |
| D | 4.80 | 5.00 | 0.189 | 0.197 | c | 0.19 | 0.25 | 0.008 | 0.010 |
| H | 5.80 | 6.20 | 0.228 | 0.244 | Θ | 0° | 8° | 0° | 8° |
| E | 3.80 | 4.00 | 0.150 | 0.157 | h | 0.25 | 0.50 | 0.010 | 0.020 |
| L | 0.40 | 1.27 | 0.016 | 0.050 | - | - | - | - | - |